

April 2015

FGA6560WDF 650 V, 60 A Field Stop Trench IGBT

Features

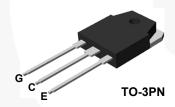
- Maximum Junction Temperature: T_J =175°C
- · Positive Temperaure Co-efficient for Easy Parallel Operating
- · High Current Capability
- Low Saturation Voltage: $V_{CE(sat)} = 1.8 \text{ V(Typ.)} @ I_C = 60 \text{ A}$
- 100% of the Parts Tested for I_{LM}(1)
- · High Input Impedance
- · Fast Switching
- · RoHS Compliant

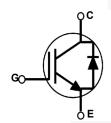
General Description

Using novel field stop IGBT technology, Fairchild's new series of field stop 3rd generation IGBTs offer the optimum performance for welder and industrial applications where low conduction and switching losses are essential.

Applications

- · Welder and Industrial Application
- · Power Factor Correction





Absolute Maximum Ratings

| Symbol | Description | | FGA6560WDF | Unit |
|---------------------|---|--------------------------|-------------|------|
| V _{CES} | Collector to Emitter Voltage | | 650 | V |
| M | Gate to Emitter Voltage | | ± 20 | V |
| V_{GES} | Transient Gate to Emitter Voltage | | ± 30 | V |
| I _C | Collector Current | @ T _C = 25°C | 120 | Α |
| 'C | Collector Current | @ T _C = 100°C | 60 | Α |
| I _{LM (1)} | Pulsed Collector Current @ T _C = 25°C | | 180 | Α |
| I _{CM (2)} | Pulsed Collector Current | | 180 | А |
| l _F | Diode Forward Current | @ T _C = 25°C | 60 | Α |
| 'F | Diode Forward Current | @ T _C = 100°C | 30 | А |
| I _{FM (2)} | Pulsed Diode Maximum Forward Curren | t | 120 | Α |
| P _D | Maximum Power Dissipation | @ T _C = 25°C | 306 | W |
| ט י | Maximum Power Dissipation | @ T _C = 100°C | 153 | W |
| T _J | Operating Junction Temperature | | -55 to +175 | °C |
| T _{stg} | Storage Temperature Range | | -55 to +175 | °C |
| T _L | Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds | 300 | °C | |

Notes

- 1. V_{CC} = 400 V, V_{GE} = 15 V, I_{C} =180 A, R_{G} = 62 Ω , Inductive Load
- 2. Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

| Symbol | Parameter | FGA6560WDF | Unit |
|------------------------|---|------------|------|
| $R_{\theta JC}(IGBT)$ | Thermal Resistance, Junction to Case, Max. | 0.49 | °C/W |
| $R_{\theta JC}(Diode)$ | Thermal Resistance, Junction to Case, Max. | 1.75 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient, Max. | 40 | °C/W |

Package Marking and Ordering Information

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|------------|---------|----------------|-----------|------------|----------|
| FGA6560WDF | FGA6560WDF | TO-3PN | Tube | - | - | 30 |

Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|--------------------------------------|--|--|------|------|------|------|
| Off Charac | eteristics | | | | | |
| BV _{CES} | Collector to Emitter Breakdown Voltage | V _{GE} = 0V, I _C = 1 mA | 650 | - | - | V |
| ΔBV _{CES} / ΔΤ _J | Temperature Coefficient of Breakdown Voltage | I _C = 1 mA, Reference to 25°C | - | 0.6 | - | V/°C |
| I _{CES} | Collector Cut-Off Current | $V_{CE} = V_{CES}, V_{GE} = 0 V$ | - | - | 250 | μА |
| I _{GES} | G-E Leakage Current | V _{GE} = V _{GES} , V _{CE} = 0 V | - | - | ±400 | nA |
| On Charac | teristics | | | | | |
| V _{GE(th)} | G-E Threshold Voltage | I _C = 60 mA, V _{CE} = V _{GE} | 4.1 | 5.6 | 7.6 | V |
| () | | I _C = 60 A, V _{GE} = 15 V | - | 1.8 | 2.3 | V |
| V _{CE(sat)} | Collector to Emitter Saturation Voltage | I _C = 60 A, V _{GE} = 15 V, T _C = 175°C | - | 2.3 | - | V |
| Dynamic C | Characteristics | | | | | |
| C _{ies} | Input Capacitance | | - | 2419 | - | pF |
| C _{oes} | Output Capacitance | $V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz | - | 82 | - | pF |
| C _{res} | Reverse Transfer Capacitance | - 1 - 11VII 12 | - | 31 | - | pF |
| Switching | Characteristics | | | | | |
| t _{d(on)} | Turn-On Delay Time | | - | 25.6 | - | ns |
| t _r | Rise Time | | - | 67.2 | - 7 | ns |
| t _{d(off)} | Turn-Off Delay Time | V _{CC} = 400 V, I _C = 60 A, | - | 71 | - / | ns |
| t _f | Fall Time | $R_G = 6 \Omega$, $V_{GE} = 15 V$, | - | 22 | - | ns |
| E _{on} | Turn-On Switching Loss | Inductive Load, T _C = 25°C | - | 2.46 | / - | mJ |
| E _{off} | Turn-Off Switching Loss | | - | 0.52 | - // | mJ |
| E _{ts} | Total Switching Loss | | - | 2.98 | - | mJ |
| t _{d(on)} | Turn-On Delay Time | | - | 22.4 | - \ | ns |
| t _r | Rise Time | | - | 63.2 | - | ns |
| t _{d(off)} | Turn-Off Delay Time | $V_{CC} = 400 \text{ V}, I_{C} = 60 \text{ A},$ | - | 77 | - | ns |
| t _f | Fall Time | $R_G = 6 \Omega$, $V_{GE} = 15 V$, | - | 22 | - | ns |
| E _{on} | Turn-On Switching Loss | Inductive Load, T _C = 175°C | - | 3.19 | - | mJ |
| E _{off} | Turn-Off Switching Loss | | - | 0.71 | - | mJ |
| E _{ts} | Total Switching Loss | | - | 3.90 | - | mJ |

Electrical Characteristics of the IGBT (Continued)

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max | Unit |
|-----------------|--------------------------|---|------|------|-----|------|
| Qg | Total Gate Charge | | - | 84 | - | nC |
| Q _{ge} | Gate to Emitter Charge | V _{CE} = 400 V, I _C = 60 A, V _{GE} = 15 V | - | 15 | - | nC |
| Q _{gc} | Gate to Collector Charge | 1 V GE = 13 V | - | 32 | - | nC |

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

| Symbol | Parameter | | Test Conditio | n | s | Min. | Тур. | Max | Unit |
|------------------|--------------------------------------|-------------------------|--------------------------------------|---|------------------------|------|------|-----|------|
| V _{FM} | Diode Forward Voltage | l- = | 30 A | | T _C = 25°C | - | 1.8 | 2.3 | V |
| FIM | Diodo i ormana voltago | 'F = | 0071 | Ī | T _C = 175°C | - | 1.7 | - | |
| E _{rec} | Reverse Recovery Energy | | | | T _C = 175°C | - | 233 | - | uJ |
| t _{rr} | Diode Reverse Recovery Time | -= | 30 A, dI _F /dt = 200 A/μs | Ī | T _C = 25°C | - | 110 | - | ns |
| 41 | Blode Reverse Recovery Time | if - 30 A, dif/di - 200 | 00 A, αιρ/αι – 200 A μο | Ī | T _C = 175°C | - | 271 | - | |
| Q _{rr} | Diode Reverse Recovery Charge | | | Ī | T _C = 25°C | - | 400 | - | nC |
| ~11 | 2.535 No. 5.55 No. 50 No. 19 Onlargo | | | Ī | T _C = 175°C | - | 1740 | - | 0 |

Figure 1. Typical Output Characteristics

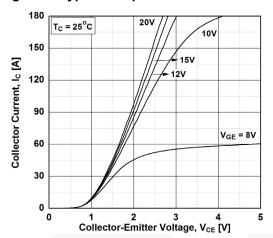


Figure 3. Typical Saturation Voltage Characteristics

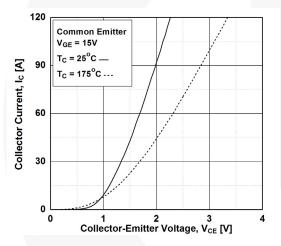


Figure 5. Saturation Voltage vs. V_{GE}

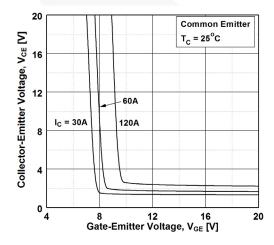


Figure 2. Typical Output Characteristics

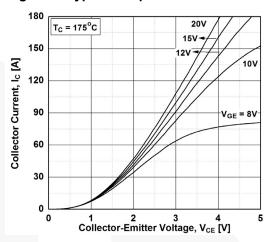


Figure 4. Saturation Voltage vs. Case
Temperature at Variant Current Level

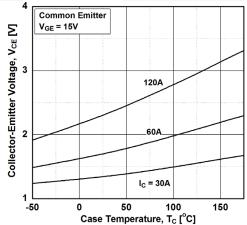


Figure 6. Saturation Voltage vs. V_{GE}

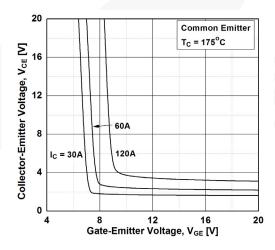


Figure 7. Capacitance Characteristics

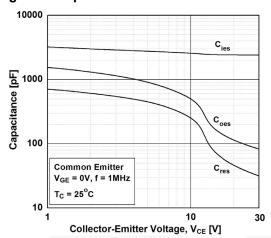


Figure 9. Turn-on Characteristics vs. Gate Resistance

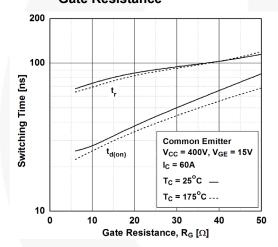


Figure 11. Switching Loss vs.
Gate Resistance

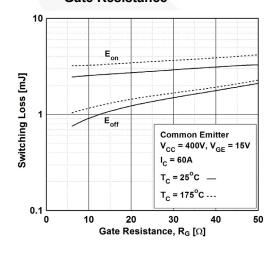


Figure 8. Gate charge Characteristics

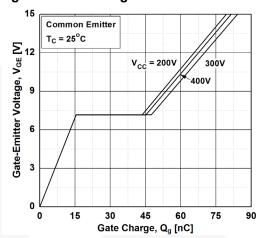


Figure 10. Turn-off Characteristics vs. Gate Resistance

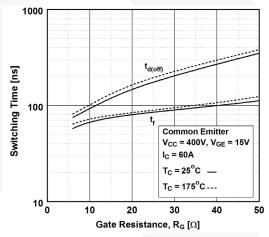


Figure 12. Turn-on Characteristics vs. Collector Current

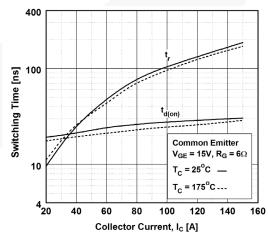


Figure 13. Turn-off Characteristics vs. Collector Current

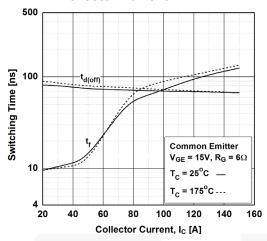


Figure 14. Switching Loss vs. Collector Current

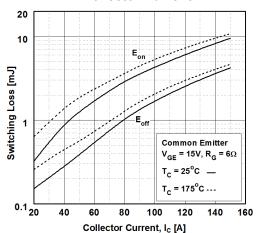


Figure 15. Load Current Vs. Frequency

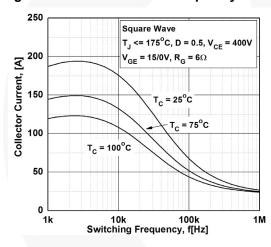


Figure 16. SOA Characteristics

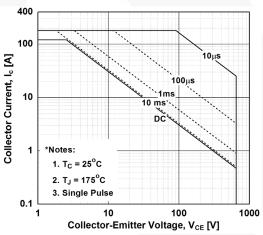


Figure 17. Forward Characteristics

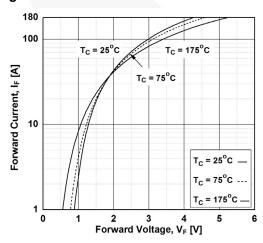


Figure 18. Reverse Recovery Current

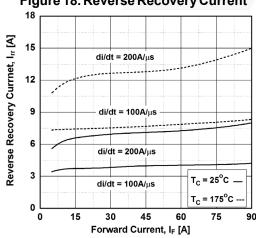


Figure 19. Reverse Recovery Time

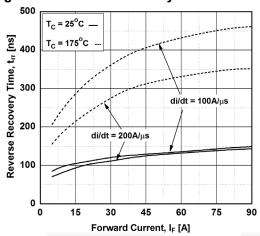


Figure 20. Stored Charge

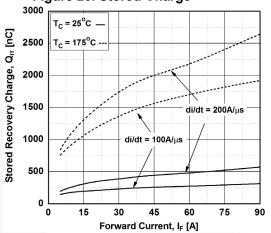


Figure 21. Transient Thermal Impedance of IGBT

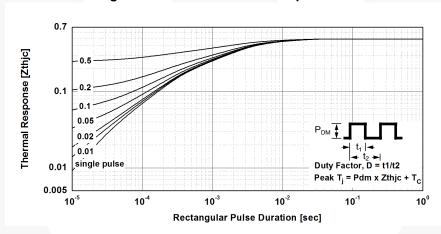
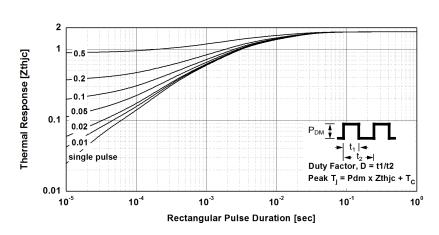
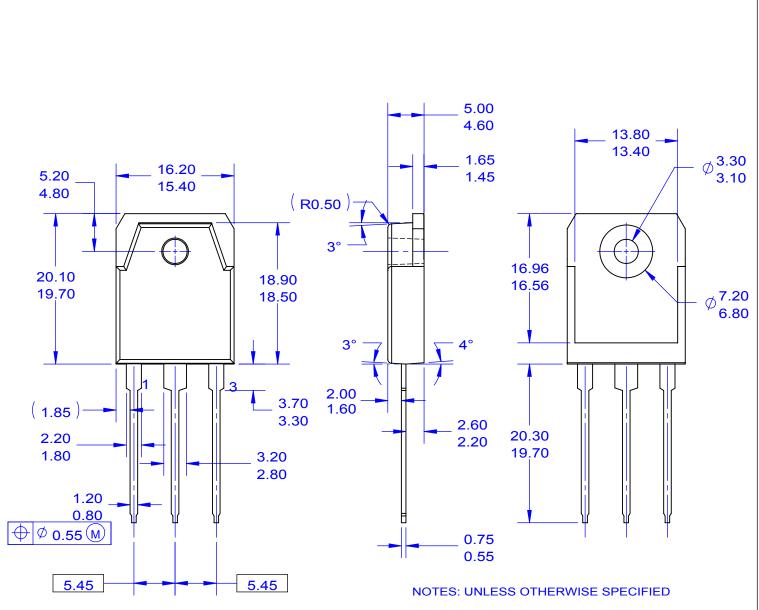
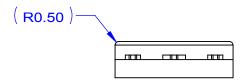


Figure 22. Transient Thermal Impedance of Diode







- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
- E) DRAWING FILE NAME: TO3PN03AREV2.
- F) FAIRCHILD SEMICONDUCTOR.







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| Definition of Terms | | | | | | | | |
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| Datasheet Identification | Product Status | Definition | | | | | | |
| Advance Information | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice. | | | | | | |
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